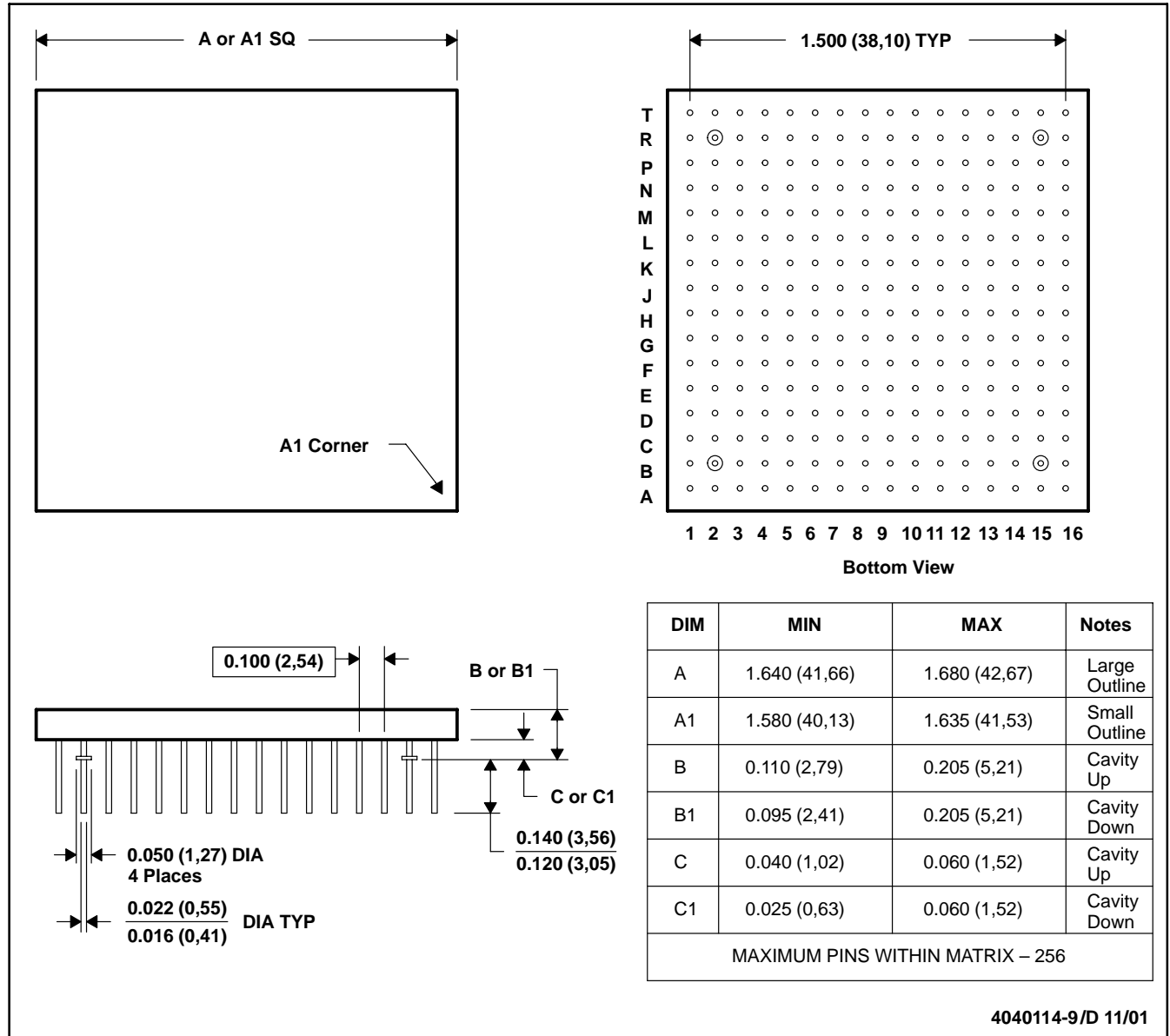


GB-GA (S-CPGA-P16 X 16)

CERAMIC PIN GRID ARRAY



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Index mark can appear on top or bottom, depending on package vendor.
 D. Pins are located within 0.010 (0,25) diameter of true position relative to each other at maximum material condition and within 0.030 (0,76) diameter relative to the edge of the ceramic.
 E. This package can be hermetically sealed with metal lids or with ceramic lids using glass frit.
 F. The pins can be gold-plated or solder-dipped.
 G. Falls within MIL-STD-1835 CMGA8-PN and CMGA20-PN, and JEDEC MO-067AH and MO-066AH, respectively

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